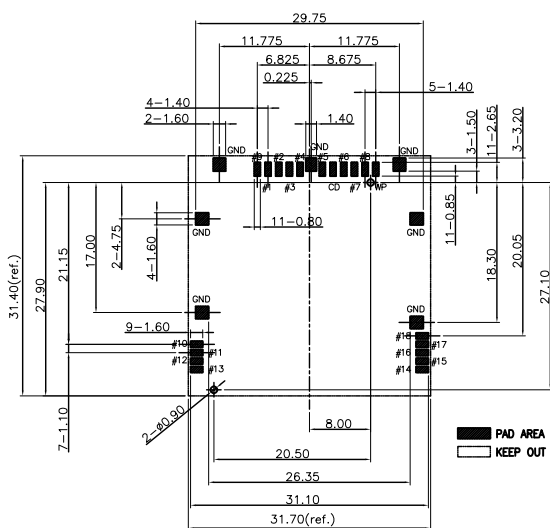
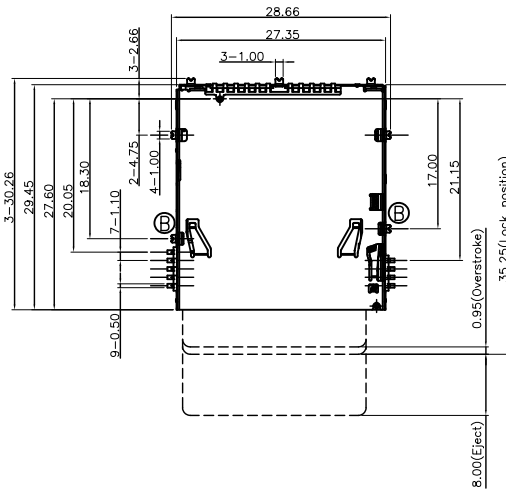
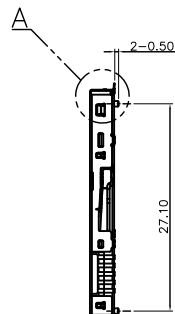
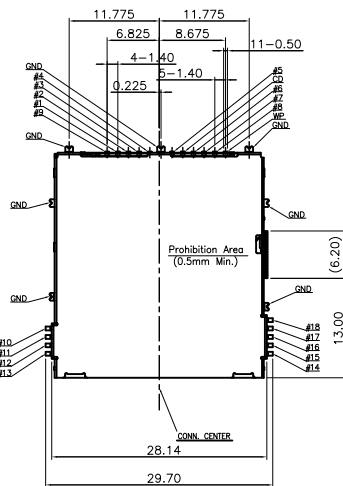
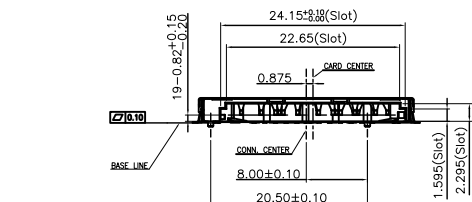


Pin Assignment

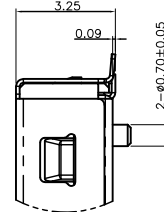
Pin#	SD Mode	UHS II Mode	SD Express Cor#	Pin#	SD Mode	UHS II Mode	SD Express Cor#
#1	CD/DAT3		PERST#	#11	DO+	PCle_Tx+	
#2	CMD			#12	DO-	PCle_Tx-	
#3	VSS1	VSS1	VSS1	#13	VSS4	VSS4	
#4	VDD	VDD1	VDD1	#14	VDD2	VDD2	
#5	CLK			#15	D1-	PCle_Rx-	
#6	VSS2	VSS2	VSS2	#16	D1+	PCle_Rx+	
#7	DAT0	RCLK+	REFCLK+	#17	VSS5	VSS5	
#8	DAT1	RCLK-	REFCLK-	#18		VDD3	
#9	DAT2		CLKREQ#	CD	Card Detect		
#10		VSS3	VSS3	WP	Write Protect		

Note:

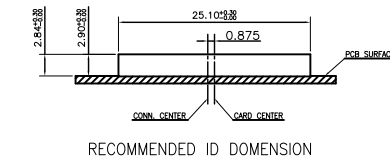
- Material:
  - 1-1. Plastic: HEAT RESISTANCE LCP, Black, HF, UL94V-0
  - 1-2. Contact: Copper Alloy
  - 1-3. Shell: Stainless Steel
- Plating:
  - 2-1. Contact:
    - Contact Area: Au 1μ" min. Plating Over Ni 50μ" min.
    - Soldertile: Gold Flash Plating Over Ni 50μ" min.
  - 2-2. Shell:
    - Solderable Ni 50μ" min. Over All
- Contact And Soldertile Coplanarity to be 0.10mm max.
- Electrical Characteristics:
  - 4-1. Contact Current Rating: 0.5Amperes.
  - 4-2. Dielectric Withstanding Voltage: AC500V r. m. s.
  - 4-3. Insulation Resistance: 1000 Megohms
  - 4-4. Contact Resistance: 100 Miliohms Maximum.
- Environmental:
  - 5-1. Operating Temperature: -25° C to +85° C.
  - 5-2. Salty spray: 48H
- Steel mesh: Recommending a metal mask more than 0.13mm chick.
  - If use a metal mask less than 0.13mm thick, please confirm solderability.



RECOMMENDED PCB LAYOUT (TOP VIEW)  
TOLERANCE UNLESS OTHERWISE SPEC ±0.05



Detail A  
Scale 4 : 1



RECOMMENDED ID DIMENSION

<p>深圳市华宇创精密电子有限公司</p>			
TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2' X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: SD 7.0 PUSH 3.25H
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. : HYCW105-SD20-325B
UNIT: mm [inch] SCALE: 1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO. : HYC-2509191504
			SHEET NO. : 1 OF 1